

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
 Stylesheet Version v1.2

EPAS ID: PAT2953935

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
DONG YOU KIM	07/18/2014
RECEIVING PARTY DATA	
Name:	HYNIX SEMICONDUCTOR INC.
Street Address:	SAN 136-1, AMI-RI, BUBAL-EUB, ICHON-SI
City:	GYEONGGI-DO
State/Country:	REPUBLIC OF KOREA
Postal Code:	467-860
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	12347005
CORRESPONDENCE DATA	
Fax Number:	(312)427-6663
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
Phone:	3124271300
Email:	debbie.szumowski@ladas.net
Correspondent Name:	RICHARD J. STREIT
Address Line 1:	LADAS & PARRY, 224 SOUTH MICHIGAN AVE.
Address Line 4:	CHICAGO, ILLINOIS 60604
ATTORNEY DOCKET NUMBER:	CU-7229 RJS/DS
NAME OF SUBMITTER:	RICHARD J. STREIT
SIGNATURE:	/RICHARD J. STREIT/
DATE SIGNED:	07/25/2014
Total Attachments: 2	
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source=2014-07-18_cu7229_assignment_kim#page2.tif	

UNITED STATES OF AMERICA
ASSIGNMENT

In consideration of the payment of ASSIGNEE to ASSIGNOR of the sum of One Dollar (\$1.00), the receipt of which is hereby acknowledged, and for other good and valuable consideration,

ASSIGNOR:

Dong You KIM
189-17 Bunji, Sachang-dong, Heungdeok-gu
Cheongju-si, Chungcheongbuk-do, Republic of Korea

hereby sells, assigns and transfers to

ASSIGNEE:

HYNIX SEMICONDUCTOR, INC.
San 136-1, Ami-ri, Bubal-eup
Icheon-si, Gyeonggi-do, Republic of Korea

and the successors, assigns and legal representatives of the ASSIGNEE the entire right, title and interest for the United States and its territorial possessions in and to, any and all improvements which are disclosed in the Application entitled SEMICONDUCTOR PACKAGE AND STACKED SEMICONDUCTOR PACKAGE HAVING THE SAME which application was filed as U.S. Serial No. 12/347,005 on December 31, 2008 and U.S. 13/650,239 filed September 28, 2012 (divisional application)

and, in and to all Letters Patent to be obtained for said invention by the above application or any continuation, division, renewal, substitute, reissue or re-examination thereof.

ASSIGNOR hereby covenants that no assignment, sale agreement or encumbrance has been or will be made or entered into which would conflict with this assignment and sale;

ASSIGNOR further covenants that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said invention and said Letters Patent and legal equivalents as may be known and accessible to ASSIGNOR and will testify as to the same in any interference or litigation related thereto and will promptly execute and deliver to ASSIGNEE or its legal representatives any and all papers, instruments or affidavits required to apply for, obtain, maintain, issue and enforce said application, said invention and said Letters

Patent and said equivalents thereof which may be necessary or desirable to carry out the purposes thereof.

IN WITNESS WHEREOF, I have set my hand and seal

July 18, 2014

Date

Dong You Kim

Dong You KIM

as per 37 CFR 1.101

10/10/14